

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC040N10NS5SC	**Issued**	16. May 2021
MA#	MA005349395		
Package	PG-WSON-8-2	**Weight***	97.74 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.175	2.22	2.22	22249	22249
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		117	
	non noble metal	zinc	7440-66-6	0.046	0.05		466	
	non noble metal	iron	7439-89-6	0.912	0.93		9328	
	non noble metal	copper	7440-50-8	37.021	37.88	38.87	378756	388667
wire	noble metal	gold	7440-57-5	0.062	0.06	0.06	638	638
encapsulation	organic material	carbon black	1333-86-4	0.038	0.04		385	
	plastics	epoxy resin	-	1.730	1.77		17703	
	inorganic material	silicondioxide	60676-86-0	17.040	17.43	19.24	174332	192420
leadfinish	non noble metal	tin	7440-31-5	1.365	1.40	1.40	13965	13965
plating	noble metal	silver	7440-22-4	0.839	0.86	0.86	8579	8579
solder	noble metal	silver	7440-22-4	0.057	0.06		580	
	non noble metal	tin	7440-31-5	0.113	0.12		1159	
	non noble metal	lead	7439-92-1	2.097	2.14	2.32	21450	23189
heat sink clip	inorganic material	phosphorus	7723-14-0	0.010	0.01		105	
	non noble metal	zinc	7440-66-6	0.041	0.04		420	
	non noble metal	iron	7439-89-6	0.822	0.84		8407	
	non noble metal	copper	7440-50-8	33.366	34.14	35.03	341361	350293
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com